

2024 Pan Pacific Strategic Electronics Symposium (Pan Pacific 2024)

**Kona, Big Island, Hawaii, USA
29 January – 1 February 2024**



**IEEE Catalog Number: CFP24B91-POD
ISBN: 979-8-3503-1853-1**

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IEEE Catalog Number:	CFP24B91-POD
ISBN (Print-On-Demand):	979-8-3503-1853-1
ISBN (Online):	978-1-944543-20-4

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TABLE OF CONTENTS

KEYNOTE

The Data Revolution Within Electronics Manufacturing: Digitization + AI/ML 1
Ryan Gamble, Daniel Gutierrez

Artificial Intelligence-Based Methods for Assessment of Accrued Damage and Remaining Use-Life
in Automotive Underhood Electronics 5
Pradeep Lall, Tony Thomas, Vishal Mehta

PLENARY SESSION

It Ain't Gonna Happen: Interplanetary Colonization 17
Hailey Mullen, Ronald Lasky

SESSION 1

Evaluation of Techniques for Intentional Contamination of PWB Substrates for Quantitative
Cleanliness Analyses 25
Adam Klett

Decoding the New IPC Cleanliness Testing Standard 33
Michael Konrad

Elevating Excellence in High-Reliability Electronics: The Personal and Lasting Legacy of Clean
PCBs 35
Justin Cody Worden

SESSION 2

Industry 4.0 Technology Adoption Issues for Small- and Medium-Sized Manufacturers and the
Role of AI to Improve Adoption Rates 37
Gregory A. Harris, Ashley Yarbrough

Dna Digital-Storage: Advantages, Approach and Technical Implementation 43
Kirsten Weide-Zaage

SESSION 3

An Improved Automated SPI Data Analysis Report Generator for Printed Circuit Board Assembly 49
Hamzeh Alshraida, Daryl Santos, Joseph Lee, Iman Dabous, Talbert Aguilar, Neil Hubble

In Situ Study of Electromigration in Eutectic Tin-Bismuth Planar Solder Joints 56
Prabjit Singh, L. Palmer, M. Hamid, T. Wassick, E. Campbell, R. F. Aspandiar, B. Franco, H. Fu, V. Vasudevan, A. Allen, K. Howell, K. Murayama, H. Zhang, A. Lifton, T. Munson, S. Middleton, Richard Coyle, M. Sarangapani

The Challenge of Lower Temperature Soldering for Large Ball-Grid Array Board-Level Assembly Process.....	62
<i>Hongwen Zhang, Tyler Richmond, Huaguang Wang, Francis Mutuku</i>	

SESSION 4

Development and Characterization of Sn99Ag0.3Cu0.7 -(ZrO2/CuO/TiO2) Nano-Composite Solder Alloys	70
<i>Balázs Illés, Halim Choi, Balázs Illés, Agata Skwarek</i>	
The Status of Low Temperature Solders.....	78
<i>Ron Lasky, Ian Tevis, Ron Lasky</i>	
An Improved Automated SPI Data Analysis Report Generator for Printed Circuit Board Assembly	85
<i>Hamzeh Alshraida, Daryl Santos, Bruce Chen, Iman Dabous, Talbert Aguilar</i>	

SESSION 5

Reliable and Automated Connection of Printed Electronics to the Aviation Electrical System	91
<i>Jan Fröhlich, Niklas Piechulek, Huong Giang Nguyen, Jörg Franke, Christoph Jürgenhake</i>	
Realization of Sustainable Additively Printed Circuits Using Aerosol-Jet Inkjet and Direct-Write Processes	97
<i>Pradeep Lall, Ved Soni, Jinesh Narangaparambil, Shriram Kulkarni, Scott Miller</i>	
Evaluation of Surface Mount Technology Reliability of Aerosol-Jet Printed Structures as Landing Pads for Surface Mounted Devices.....	106
<i>Eddie Quinn, Jesse Singer, Laura Jean Weidman, Angel Irizarry, Marcus Lee</i>	

SESSION 6

Recent Developments and Challenges in Battery Safety with Solid-State Technology	115
<i>Sierra Freitas, Weiyang Li</i>	
Swelling in Lithium-Ion Pouch Batteries	121
<i>Michael Osterman, Sahithi Maddipatla</i>	

SESSION 7

Physics-Informed Machine Learning for Solder Design and Reliability Prediction for Electronics	125
<i>Jia Liu, Qais Qasimeh</i>	
Adiabatic & Isothermal Humidification for Electronics Manufacturing: the Science of Humidity Control in Manufacturing	132
<i>Richard Williams</i>	

SESSION 8

Implementation of the Product Reliability Program.....	138
<i>John Cooper</i>	

Advanced Analysis and Monitoring of Failure Mechanisms in Microelectronics Metallization..... 144
André Clausner, Matthias Kraatz, Sonja Crocoll, Marc Schuchart, Verena Hein

SESSION 9

The Comparison of the Reliability Performance of Different Top Metal Materials in MEMS Applications..... 149
Verena Hein, Kirsten Weide-Zaage, André Clausner

Glass and Glass/LTCC Interposers as Heterogenous Integration Platform 155
Jens Müller, Mahsa Kaltwasser, Heike Bartsch, Arne Behrens, Thomas Handte, Julian Wüster, Stefan Sinzinger

SESSION 10

New Solutions to Combat Counterfeits 162
Adam Hook

Evaluating Electronic Component Testing with AI-Based Test Augmentation 181
Charlie Polidoro

Author Index